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(54) **PACKAGED DEVICE ADAPTER WITH
PARAMETER INDICATION**

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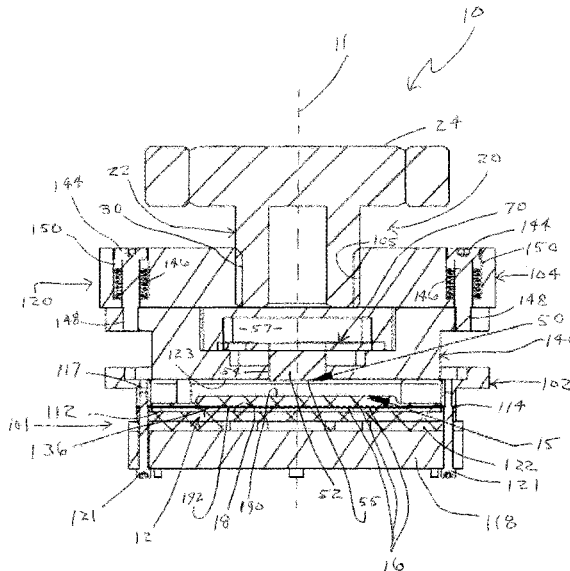
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See application file for complete search history.

(57) **ABSTRACT**

An adapter apparatus and method includes using an adapter body defining a socket cavity configured to receive a packaged device and a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body. A measurement apparatus associated with the socket lid assembly may include a measurement element (e.g., temperature sensing element, compressible element, etc.) that is configured to contact a packaged device received in the socket cavity when the socket lid assembly closes the socket cavity and applies a force upon the packaged device (e.g., a measurement signal is generated with use of the measurement element that is configured to contact the packaged device). An indicator may be configured to display a parameter based on the measurement signal (e.g., a count, a temperature, etc.).

20 Claims, 10 Drawing Sheets



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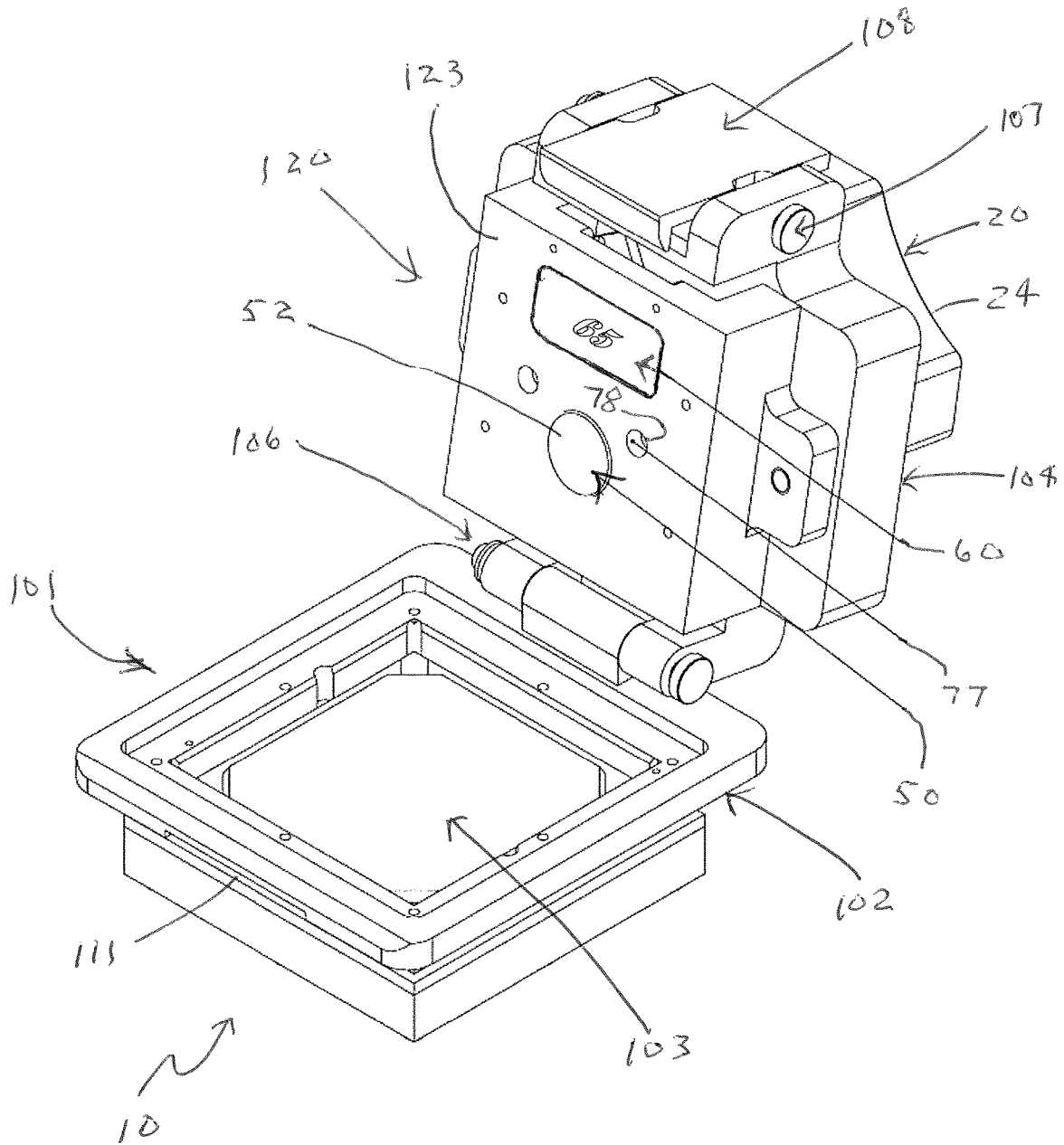


FIG. 1

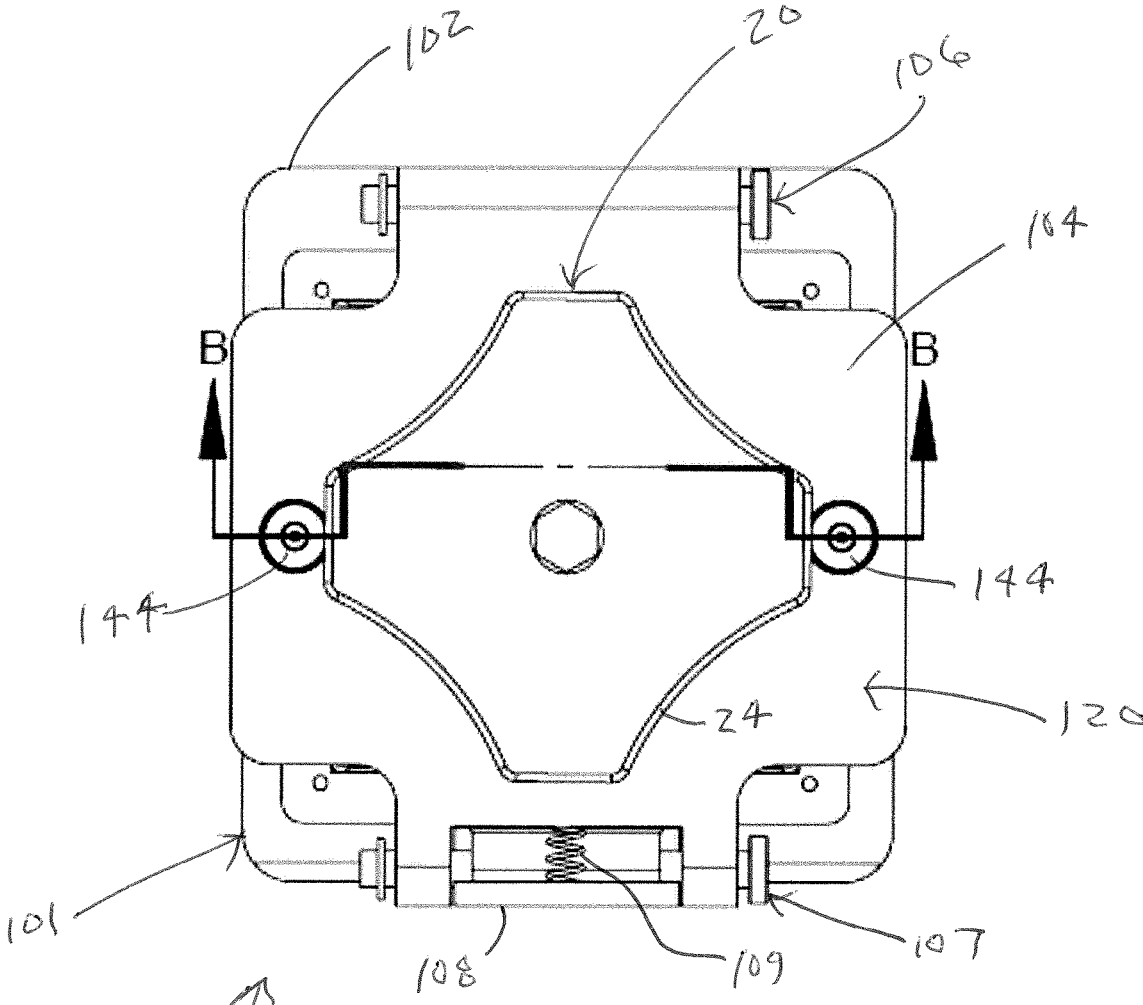
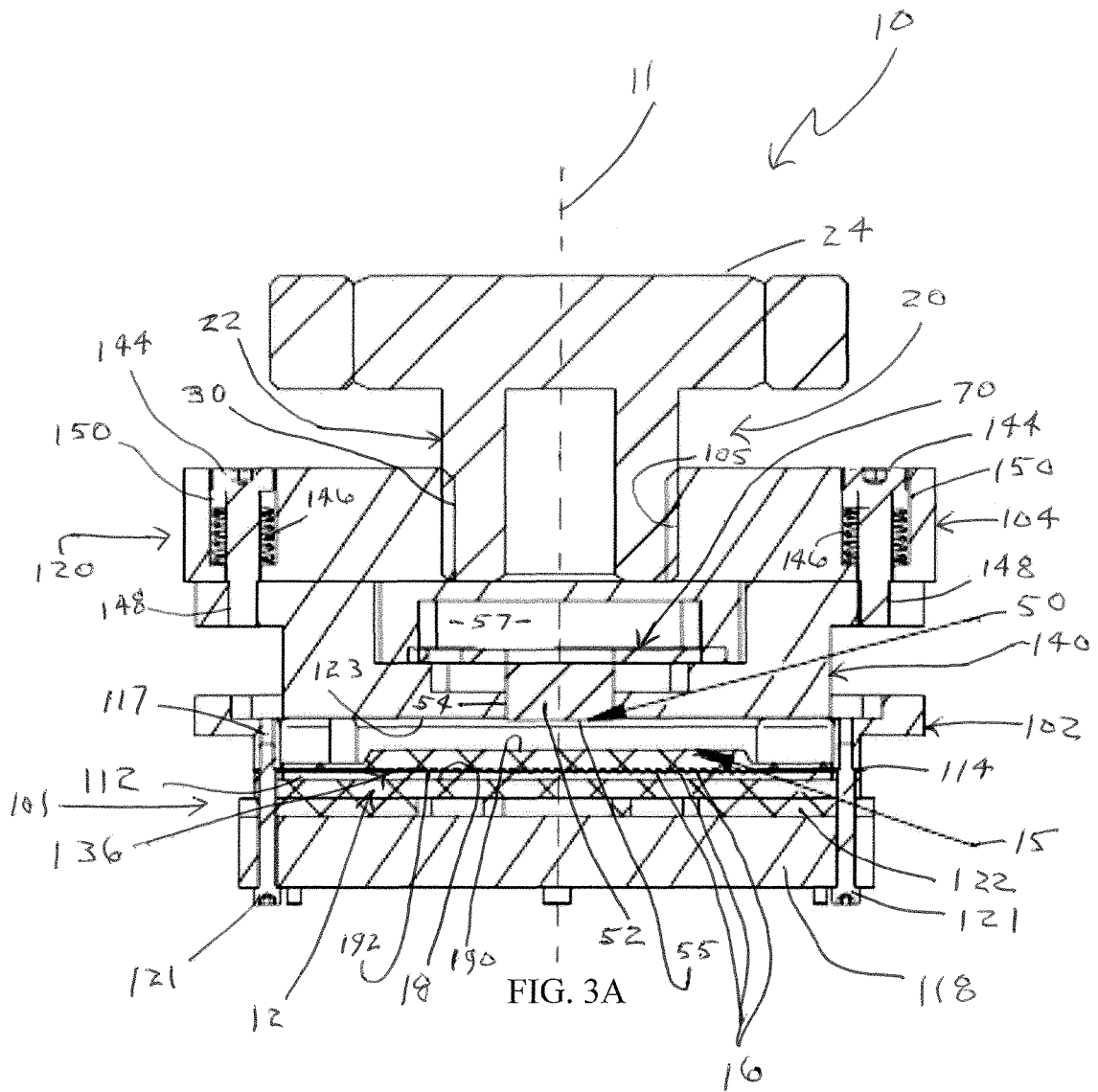
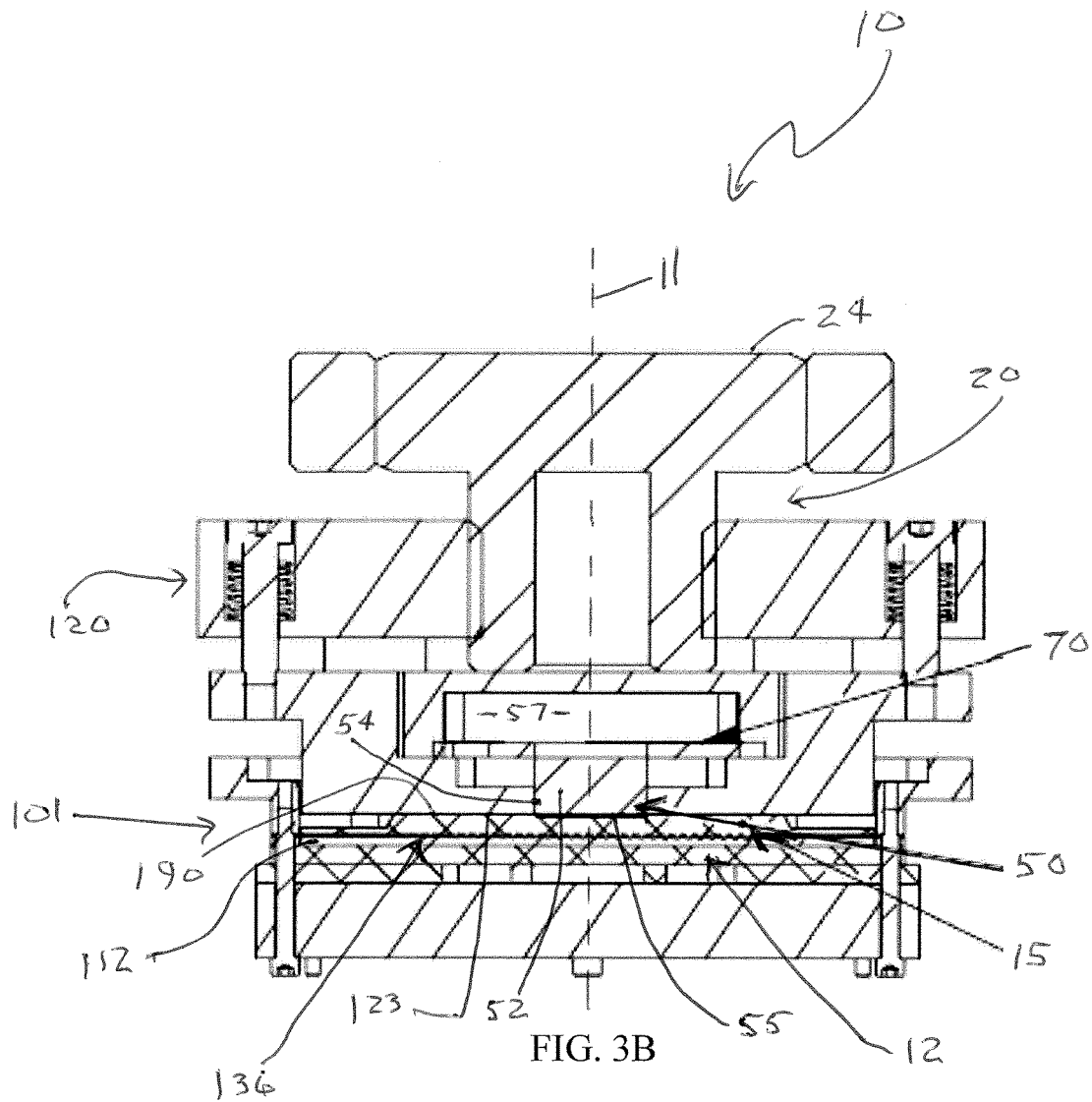


FIG. 2





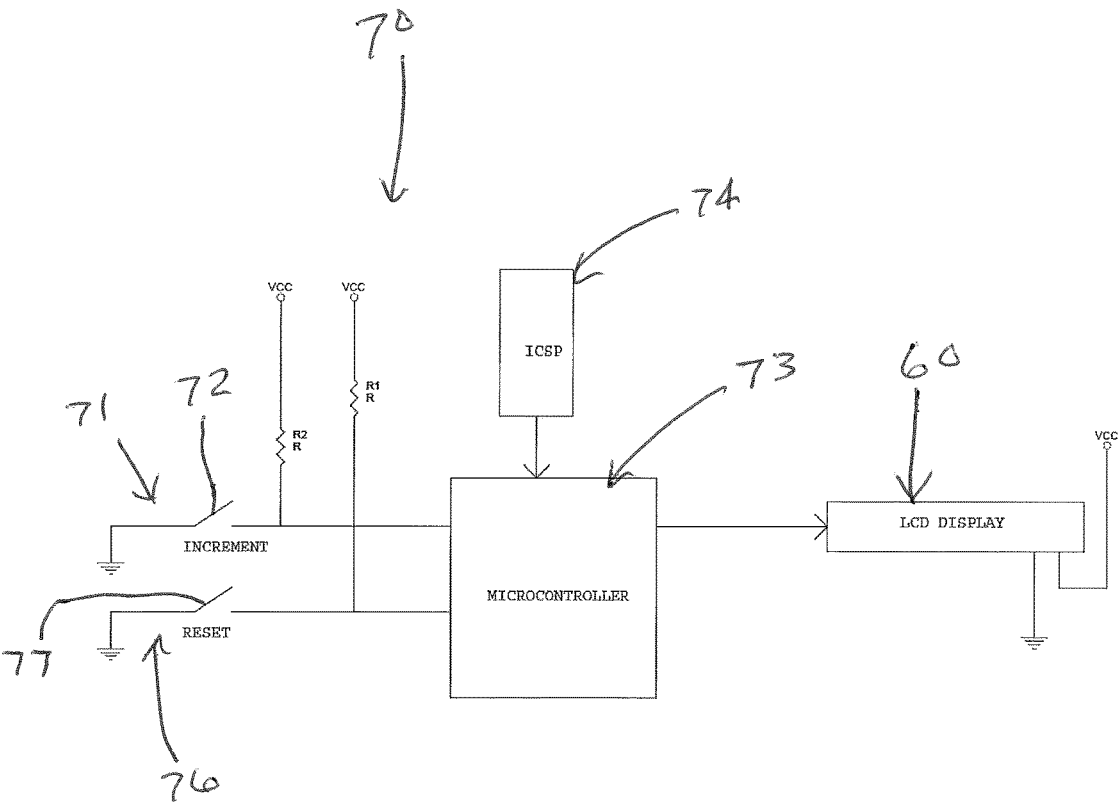


FIG. 4

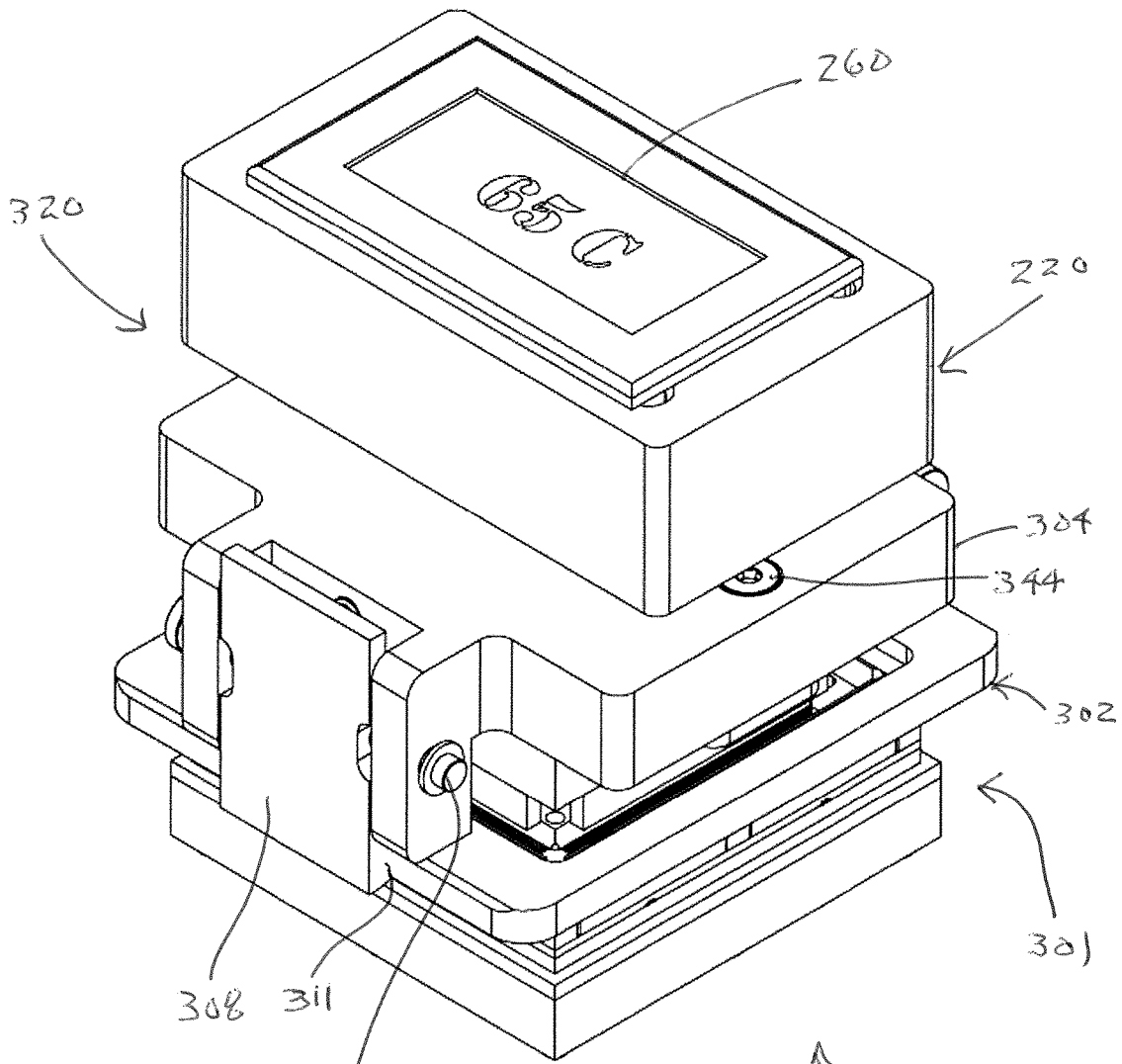
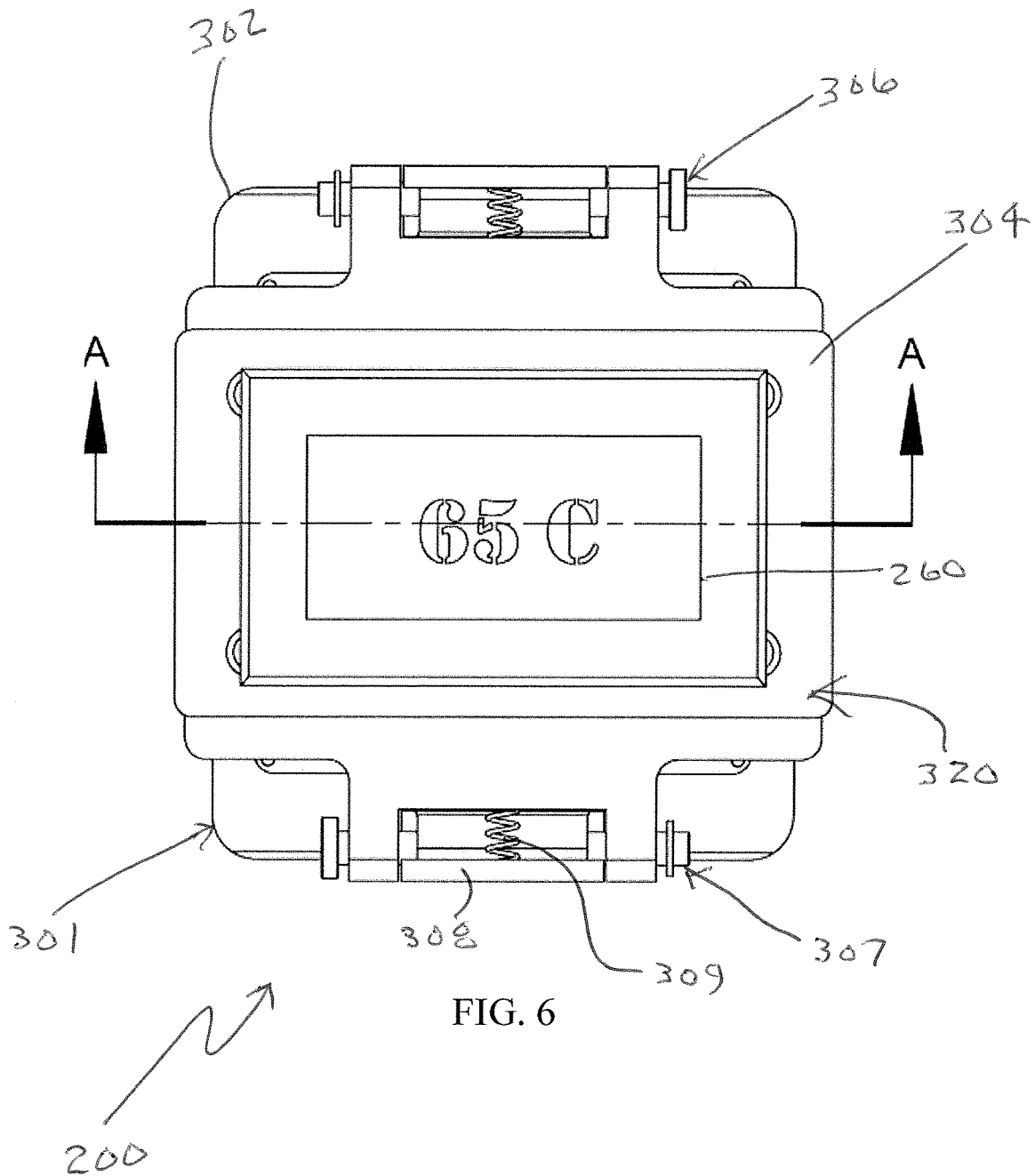


FIG. 5



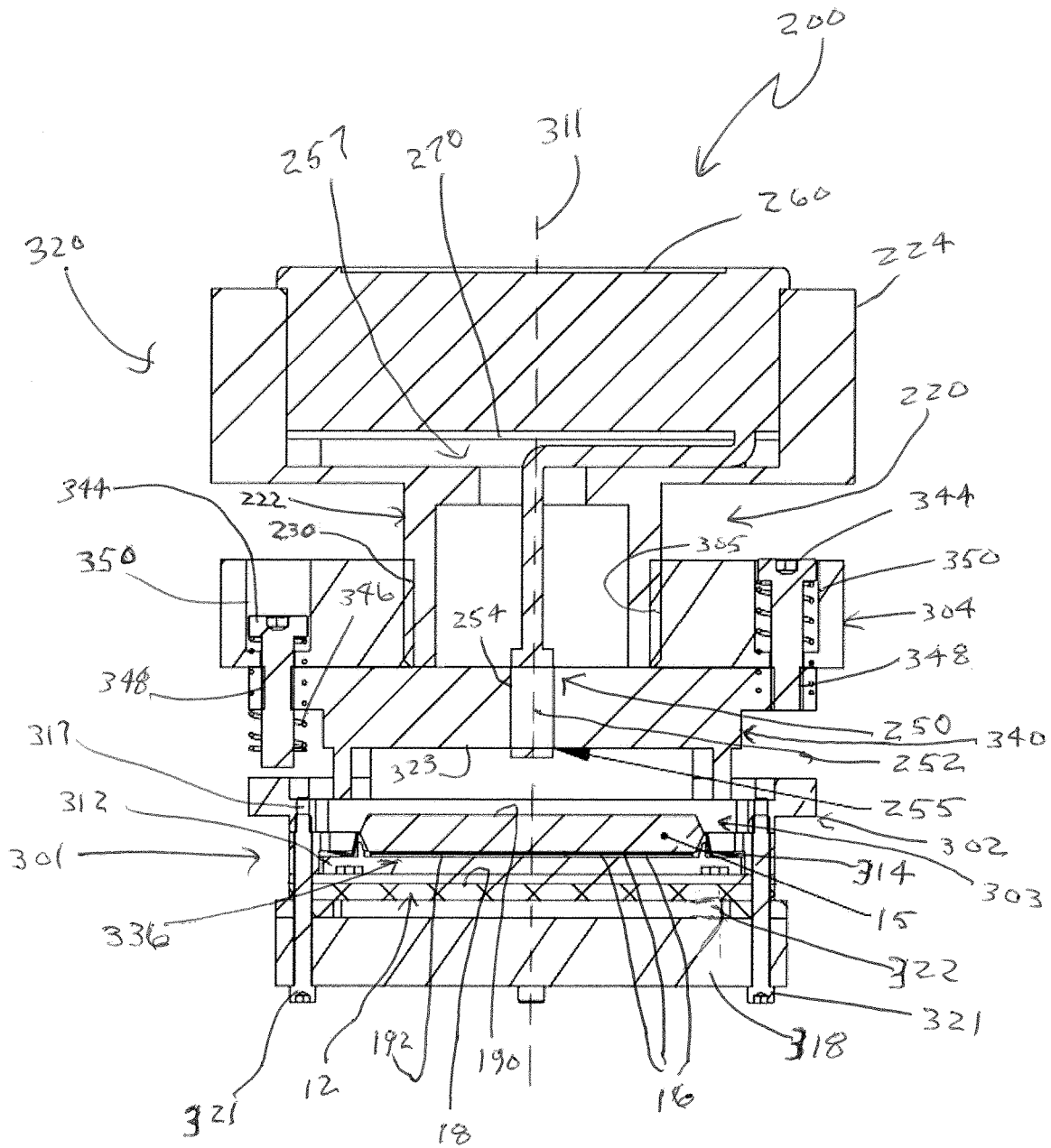


FIG. 7A

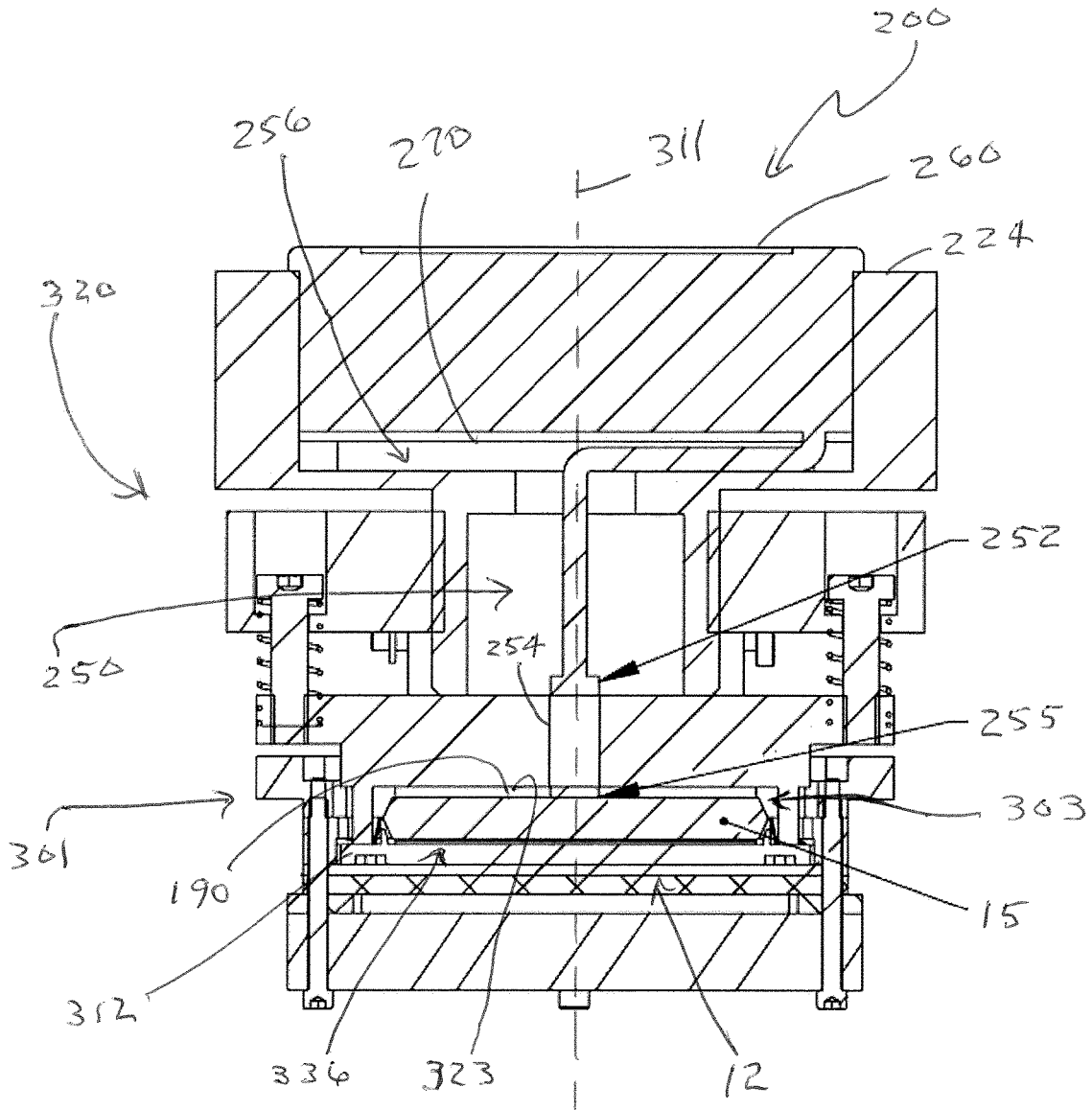


FIG. 7B

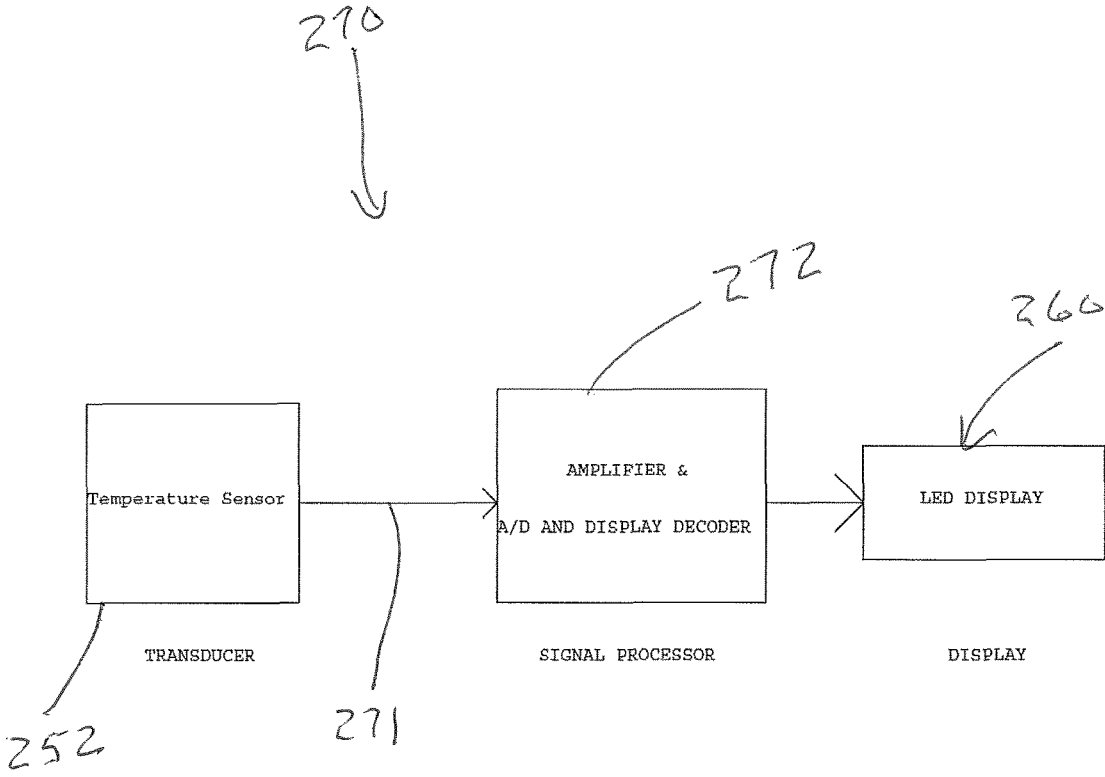


FIG. 8

PACKAGED DEVICE ADAPTER WITH PARAMETER INDICATION

BACKGROUND

The present disclosure relates to electrical adapters and methods using such adapters. More particularly, the present disclosure pertains to employing a parameter indicating apparatus with adapters for packaged integrated circuit devices (e.g., micro lead frame packages, micro lead chip carriers, quad flat no lead packages, and micro ball grid array packages, etc.) and methods for using such adapters.

Certain types of integrated circuit packages are becoming increasingly popular due to their occupancy area efficiency. In other words, they occupy less area on a target board on which they are mounted while providing a high density of contact terminals. For example, one such high density package type is a micro lead frame package. Generally, such packages contain an integrated circuit having its die bond pads electrically connected to respective conductive contact lead elements (e.g., lands) that are distributed on a surface of the package (e.g., the bottom surface of the package, for example, in an array).

A target printed circuit board upon which the package is to be mounted typically has formed on its surface a corresponding array of conductive pads which are aligned with the conductive contact lead elements of the package for electrically mounting the package on the target board. The target board typically includes other conductive traces and elements which lead from the array of conductive pads used for mounting the package to other circuitry on the board for connecting various components mounted thereon.

Typically, to mount such a package to a target board, solder material (e.g., solder balls) is provided in a manner corresponding to the array of conductive pads on the target board. The package is positioned with the contact lead elements in contact with the solder material corresponding to the array of conductive pads on the target board. The resulting structure is then heated until the solder material is melted and fused to the contact lead elements of the package.

Such area efficient packaging, e.g., micro lead frame packages or micro ball grid array packages, provide a high density of terminals at a very low cost. Also, this packaging provides for limited lead lengths. The limited lead lengths may reduce the risk of damage to such leads of the package, may provide for higher speed product, etc.

Generally, circuit boards and/or components mounted thereon are tested by designers as the circuit boards are being developed. For example, for a designer to test a circuit board and/or a package mounted thereon, the designer must first electrically connect the package to the target circuit board (e.g., using solder balls).

As described above, this may include mounting the package on the target board and heating the solder material (e.g., solder spheres) to fuse the solder material to the contact lead elements of the package. Therefore, the package may be prevented from being used again. It is desirable for various reasons to use packaged device adapters for mounting the packages and reuse such packages after testing. For example, such device packages may be relatively expensive. Further, for example, once attached, the solder material and/or the contact lead elements (e.g., land pads) are not accessible for testing. In addition, it is often difficult to rework the circuit board with the packages soldered thereon.

Various adapters are available for use in electrically connecting a package to a target board for one or more

purposes. For example, U.S. Pat. No. 7,565,843 to Palaniappa et al., entitled "Packaged Device Adapter with Torque Indicating Assembly," issued 28 Jul. 2009; U.S. Pat. No. 6,533,589 to Palaniappa et al., entitled "Packaged Device Adapter Assembly," issued 18 Mar. 2003; U.S. Pat. No. 6,394,820 to Palaniappa et al., entitled "Packaged Device Adapter Assembly And Mounting Apparatus," issued 28 May 2002; U.S. Pat. No. 5,791,914 to Loranger et al., entitled "Electrical Socket With Floating Guide Plate," issued 11 Aug. 1998; U.S. Pat. No. 4,460,223 to Brown et al., entitled "Cover For Chip Carrier Socket," issued 17 Jul. 1984; U.S. Pat. No. 5,892,245 to Hilton, entitled "Ball grid Array Package Emulator," issued 6 Apr. 1999; and U.S. Pat. No. 5,730,620 to Chan et al., entitled "Method And Apparatus For Locating Electrical Circuit Members," issued 24 Mar. 1998, all describe various adapters that are used for mounting or locating packaged devices. Many of such adapters include lid assemblies for applying force or pressure on the packaged devices such that electrical contact of the packaged device conductive pads (e.g., pads on the bottom surface of the device) to corresponding contacts (e.g., a conductive elastomer or other arrangement of conductive elements, or further target board conductive land pads) is achieved.

In packaged device testing, measurement of various parameters with respect to the device under test or the adapter used for testing may be useful.

SUMMARY

The present disclosure provides a measurement apparatus (e.g., for counting and displaying the number of times an adapter is used, for measuring and displaying temperature of a packaged device under test, etc.) that, for example, may be employed with a packaged device adapter for use in mounting or locating high density integrated circuit packages (e.g., micro lead frame packages, micro lead chip carriers, quad flat no lead packages, and micro ball grid array packages, etc.).

One exemplary embodiment of an adapter apparatus according to the present disclosure is for use with a packaged device having a plurality of contact elements disposed on a surface thereof. The adapter apparatus includes an adapter body defining a socket cavity configured to receive a packaged device, a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto, and an actuation apparatus associated with the socket lid assembly (i.e., wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon the packaged device), counter circuitry configured to increment a count when the actuation apparatus is actuated, and an indicator configured to display a parameter based on the incremented count.

In one or more embodiments of the adapter apparatus, the indicator may be configured to display a count of the number of times the actuation apparatus is actuated. Further, the adapter apparatus may include reset circuitry to reset the count to zero.

Further, in one or more embodiments of the adapter apparatus, the actuation apparatus associated with the socket lid assembly may include a compressible element at a surface of the socket lid assembly that is actuated upon contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon

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the packaged device, the indicator may include a display viewable only when the socket lid assembly is in an open state such that a packaged device may be received within the socket cavity, the counter circuitry may be integrated into the socket lid assembly, and/or the adapter apparatus may further include a temperature sensing apparatus associated with the socket lid assembly (e.g., wherein the temperature sensing apparatus may include a sensing element that is configured to touch a packaged device received in the socket cavity to sense the temperature of the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device) and a temperature indicator configured to display a parameter based on the sensed temperature.

One exemplary embodiment of a method of testing packaged devices using an adapter apparatus according to the present disclosure (e.g., wherein each of the packaged devices may include a plurality of contact elements disposed on a surface thereof) may include providing an adapter body defining a socket cavity therein configured to receive a packaged device, providing a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto, positioning a packaged device in the socket cavity, closing the socket lid assembly to apply a force upon the packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto, and incrementing a counter upon closing the socket lid assembly and applying a force upon the packaged device received in the socket cavity of the adapter body.

One or more embodiments of the method may include repeating the positioning of a packaged device in the socket cavity, closing the socket lid assembly to apply a force upon the packaged device received in the socket cavity of the adapter body, and incrementing a counter upon closing the socket lid assembly for one or more additional packaged devices. A count may then be displayed based on the incremented counter.

Further, in one or more embodiments, the method may include one or more of the following features and/or processes: resetting the incremented counter; displaying the count only when the socket lid assembly is in an open state such that a packaged device may be received within the socket cavity; providing an actuation apparatus associated with the socket lid assembly (e.g., wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon the packaged device) and incrementing a counter based on the actuation of the actuation apparatus; a compressible element at a surface of the socket lid assembly that is actuated upon contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device; and/or displaying a temperature of the packaged device upon closing the socket lid assembly and applying a force upon the packaged device received in the socket cavity of the adapter body.

Another exemplary embodiment of an adapter apparatus according to the present disclosure is for use with a packaged device having a plurality of contact elements disposed on a surface thereof. The exemplary adapter apparatus may include an adapter body defining a socket cavity configured to receive a packaged device, a socket lid assembly configured to apply a force upon a packaged device received in the

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socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto, and a measurement apparatus associated with the socket lid assembly (e.g., wherein the measurement apparatus may include a measurement element that is configured to contact a packaged device received in the socket cavity when the socket lid assembly closes the socket cavity and applies a force upon the packaged device). A measurement signal may be generated with use of the measurement element that is configured to contact the packaged device and an indicator may be configured to display a parameter based on the measurement signal.

In one or more embodiments of the exemplary adapter apparatus, the measurement apparatus may include an actuation apparatus associated with the socket lid assembly (e.g., wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon a packaged device); the indicator being configured to display a count of the number of times the actuation apparatus is actuated.

Further, in one or more embodiments of the exemplary adapter apparatus, the measurement apparatus associated with the socket lid assembly may include a temperature sensing apparatus associated with the socket lid assembly (e.g., wherein the temperature sensing apparatus may include a sensing element that is configured to touch a packaged device received in the socket cavity to sense the temperature of the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device); the indicator being configured to display a parameter based on the sensed temperature.

Further, in one or more embodiments of the adapter apparatus, a thermocouple may be configured at a surface of the socket lid assembly such that the thermocouple is in contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, the indicator may be viewable when the socket lid assembly is in a closed state when the socket lid assembly closes the socket cavity and applies a force upon a packaged device received within the socket cavity, and/or the measurement apparatus may include measurement and display circuitry integrated into the socket lid assembly.

Another exemplary embodiment of a method of testing packaged devices using an adapter apparatus according to the present disclosure (e.g., wherein each of the packaged devices may include a plurality of contact elements disposed on a surface thereof) may include providing an adapter body defining a socket cavity therein configured to receive a packaged device, providing a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto, providing a measurement apparatus associated with the socket lid assembly (e.g., wherein the measurement apparatus may include a measurement element that is configured to contact a packaged device received in the socket cavity when the socket lid assembly closes the socket cavity and applies a force upon the packaged device), positioning a packaged device in the socket cavity, closing the socket lid assembly to apply a force upon the packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto (e.g., a measurement signal begin generated using

the measurement element), and displaying a parameter based on the measurement signal.

In one or more embodiments of the method, providing the measurement apparatus may include providing an actuation apparatus associated with the socket lid assembly (e.g., wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon a packaged device), and further, displaying a parameter based on the measurement signal may include displaying a count of the number of times the actuation apparatus is actuated.

Further, in one or more embodiments of the method, providing the measurement apparatus may include providing a temperature sensing apparatus associated with the socket lid assembly (e.g., wherein the temperature sensing apparatus may include a temperature sensing element, for example, a thermocouple, that is configured to touch a packaged device received in the socket cavity to sense the temperature of the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device), and further, displaying a parameter based on the measurement signal may include displaying a parameter based on the sensed temperature.

Further, in one or more embodiments of the method, displaying a parameter based on the sensed temperature may include displaying a temperature at a location viewable when the socket lid assembly is in a closed state when the socket lid assembly closes the socket cavity and applies a force upon a packaged device received within the socket cavity.

The above summary is not intended to describe each embodiment or every implementation of the present disclosure. Advantages, together with a more complete understanding of the disclosure, will become apparent and appreciated by referring to the following detailed description and claims taken in conjunction with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a perspective view of an exemplary packaged device adapter apparatus (i.e., in an open state) including a measurement apparatus (e.g., counting components) according to the present disclosure.

FIG. 2 is a top view of the exemplary packaged device adapter apparatus of FIG. 1.

FIGS. 3A and 3B are cross-section views of the exemplary adapter apparatus shown in FIGS. 1-2 taken along line B-B in FIG. 2, in an uncompressed and compressed state, respectively.

FIG. 4 is an exemplary embodiment of counter circuitry that may be integrated into the socket lid assembly of the adapter apparatus shown in FIGS. 1-3.

FIG. 5 is a perspective view of another exemplary packaged device adapter apparatus (i.e., in a closed state) including a measurement apparatus (e.g., temperature sensing apparatus) according to the present disclosure.

FIG. 6 is a top view of the exemplary packaged device adapter apparatus of FIG. 5.

FIGS. 7A and 7B are cross-section views of the exemplary adapter apparatus shown in FIGS. 5-6 taken along line A-A in FIG. 6, in an open position (e.g., uncompressed) and a closed position (e.g., compressed state), respectively.

FIG. 8 is an exemplary embodiment of temperature sensing and display circuitry that may be integrated into the socket lid assembly of the adapter apparatus shown in FIGS. 5-7.

DETAILED DESCRIPTION OF THE EMBODIMENTS

Generally, a packaged device adaptor apparatus for use with packaged devices (e.g., high density devices) which employs various types of measurement apparatus (e.g., for counting and displaying the number of times an adapter is used, for measuring and displaying temperature of the packaged device under test, etc.), as well as methods employing such adaptor apparatus, shall be described herein. Illustrative packaged device adaptor apparatus (e.g., adaptor apparatus 10 and 200) shall be described with reference to FIGS. 1-8.

One skilled in the art will recognize from the description herein that the various illustrative embodiments described include some features or elements included in other illustrative embodiments and/or exclude other features. However, packaged device adaptor apparatus may include any combination of elements selected from one or more of the various embodiments as described herein with reference to FIGS. 1-8. For example, as will be readily apparent from the description below, one or more different types of socket bodies, including, for example, a clamshell socket, a pogo pin socket, etc., may utilize the measurement features described herein. For example, measurement and display apparatus of an adapter apparatus described in combination with one embodiment may be used in a different embodiment (e.g., a counting feature may be used alone or in combination with a temperature sensing feature, a temperature sensing feature may be used alone or in combination with other measurement features, etc.). One skilled in the art will readily recognize that an adaptor apparatus employed for one or more various purposes (e.g., locating a packaged device on a target board, mounting a packaged device for testing purposes relative to a target board, etc.) may benefit from the features described herein.

FIG. 1 is a perspective view of an exemplary packaged device adaptor apparatus 10. The exemplary packaged device adaptor apparatus 10 may be mounted relative to a target board 12 (e.g., such as shown in FIG. 3). A top view of the exemplary packaged device adaptor apparatus 10 is shown in FIG. 2. FIGS. 3A and 3B are cross-section views of the exemplary adapter apparatus 10 shown in FIGS. 1-2 taken along line B-B in FIG. 2, in an uncompressed and compressed state, respectively.

The adaptor apparatus 10 is for use with a packaged device 15 (see FIGS. 3A and 3B) having a plurality of contact elements 16 disposed on a surface 192 (e.g., bottom surface) thereof. The adaptor apparatus 10 includes an adaptor body 101 and a socket lid assembly 120. The adaptor body 101 defines a socket cavity 103 configured to receive the packaged device 15 such that, for example, the plurality of contact elements 16 of the packaged device 15 are aligned with arranged conductive elements. For example, the conductive elements may include conductive elements 136 as shown in FIGS. 3A and 3B which form a portion of adaptor apparatus 10. However, the conductive elements may include other elements in one or more other applications as will be apparent from the description herein, such as, for example, an arranged pattern of contacts on a surface (e.g., surface 18 of a target board 12 (see FIGS. 3A and 3B)). As shown in FIG. 1, the adapter apparatus is in an open state (e.g., the lid assembly 120 being in an open position such that a packaged device may be received within the socket cavity 103.

The socket lid assembly 120 includes a lid portion 104 and a torque assembly 20 provided for use in applying a

force upon the packaged device **15** received in the socket cavity **103** defined by the adaptor body **101**. At least one embodiment, the torque assembly **20** includes a threaded interface member **22**; the threaded interface member **22** including a threaded portion **30** configured to mate with the threaded opening **105** of the lid portion **104**. Further, at least in one embodiment, the torque assembly **20** includes a torque applicator **24** for grasping and applying torque (e.g., the torque applicator **24** being coupled to the threaded interface member **22** such that torque applied to the torque applicator **24** is transferred to the threaded interface member **22** to move the threaded portion **30** thereof into the threaded opening **105** of the lid portion **104**. Turning of the torque assembly **20** into the threaded opening **105** assists in asserting a force (e.g., either directly or indirectly) onto packaged device **15** such as, for example, to provide the contact elements **16** of the packaged device **15** into electrical contact with an arrangement of conductive elements (e.g., conductive elements **136**, such as elements of a conductive elastomer, pads, etc.) corresponding thereto.

Further, at least in one or more embodiments, the socket lid assembly **120** may include measurement apparatus associated with the lid assembly **120**. The measurement apparatus may generally include at least one measurement element that is configured to contact a packaged device **15** received in the socket cavity **103** when the socket lid assembly **120** closes the socket cavity **103** and applies a force upon the packaged device **15**. In at least one embodiment, a measurement signal is generated with use of the measurement element that is configured to contact the packaged device **15** when the socket lid assembly **120** is closed and applies force upon the packaged device **15**. Still further, in one or more embodiments, the socket lid assembly **120** may include an indication apparatus or an indicator that is configured to display a parameter based on the measurement signal.

For example, as shown in FIGS. 1-3, the measurement apparatus, as further described herein, may include an actuation apparatus **50** associated with the lid assembly **120**. The actuation apparatus **50** may be actuated when the socket lid assembly **120** closes the socket cavity **103** and applies a force upon a packaged device **15**. An indicator **60** as shown in FIG. 1 may be used to display a count of the number of times the actuation apparatus **50** is actuated.

Further, for example, as shown in FIGS. 5-7, the measurement apparatus, as further described herein, may include a temperature sensing apparatus **250** that includes a sensing element **252** configured to touch a packaged device **15** received in the socket cavity **303** to sense the temperature of the packaged device **15** when the socket lid assembly **320** closes the socket cavity **303** and applies a force upon the packaged device **15**. An indicator **260**, as shown in FIG. 5, may be configured to display a parameter based on the sensed temperature (e.g., the temperature or a parameter that indicates the temperature is too high).

At least in one embodiment, the components of the adaptor apparatus **10** (e.g., including the socket lid assembly **120** which includes torque assembly **20** and lid portion **104**, the adapter body **101**, and the socket cavity **103**) lie along axis **11**. The axis **11** is generally orthogonal, at least in one embodiment, to the target board **12**.

The packaged device **15** may be any packaged device having a plurality of contact elements **16** disposed on a surface thereof. In one exemplary embodiment, the packaged device is a device having a high density of contact terminals (e.g., lands, solder spheres, bumps, contact pads, leads, etc.) disposed on the surface thereof. For example, the

high density packaged device may be a micro lead frame package, a micro lead chip carrier, a quad flat no-lead package, micro ball grid array package, or any other type of package such as a ball grid array package, a chip scale package, a flip chip package, a flat package, a quad flat package, a small outline package, a land grid array package, or any other package having contact elements disposed on a surface thereof. Although one packaged device **15** is shown in the figures, the present disclosure is in no manner limited to the use of the illustrative adaptor apparatus embodiments described herein with packages that are configured in such a manner. Rather, adaptor apparatus which employ features as described herein may be used with any packaged device having contact elements disposed on a surface thereof.

In one embodiment, as shown in FIGS. 3A and 3B, packaged device **15** includes an upper surface **190** and the lower surface **192**, in addition to one or more side surfaces extending therebetween at the perimeter of the packaged device **15**. The plurality of contact elements **16** are disposed at least at the lower surface **192**. For example, the contact elements **16** may be distributed in an array along orthogonal X and Y axes, or the contact elements (e.g., lands) may be distributed along the outer portions of the lower surface **192** proximate the perimeter thereof. However, any arrangement of contact elements **16** may be accommodated.

The adaptor body **101** may be provided by any number of components that define the socket cavity **103** configured to receive the packaged device **15** therein and the socket lid assembly **120** may be provided by any number of components that are configured to close the socket cavity **103** and apply a force to a packaged device received therein. In at least one or more embodiments, the packaged device is received within the socket cavity **103** such that the plurality of contact elements **16** of the packaged device **15** are aligned with arranged conductive elements corresponding thereto (e.g., pads of a target board, conductive elastomer elements, etc.). Apart from being operable to receive the packaged device **15** in the socket cavity, the configuration of the adaptor body **101** may take any number of forms. Apart from being able to close the socket cavity and apply a force upon the packaged device, the socket lid assembly may take any number of forms. For example, the adaptor body and the socket lid assembly may include elements such as those found in U.S. Pat. No. 7,565,843, U.S. Pat. No. 6,533,589, U.S. Pat. No. 6,394,820, U.S. Pat. No. 5,791,914, U.S. Pat. No. 4,460,223, U.S. Pat. No. 5,892,245, and/or U.S. Pat. No. 5,730,620. For example, such adaptor bodies may be configured for receiving a packaged device **15** to be located or aligned with contact pads on a target board, may be configured for receiving a packaged device such that the contact elements **16** thereof are positioned adjacent a conductive elastomer, or may include, for example, a clamshell socket body or pogo pin socket as shown and described generally herein with reference to the figures.

As shown in FIGS. 1-3, the adaptor body **101** (e.g., a part of a clamshell socket) includes a socket base **102** defining at least a part of the socket cavity **103** configured to receive a packaged device **15**. The socket lid assembly **120** used to close the socket cavity **103** is hinged to the socket base **102** using a hinge pin or pins **106**.

Further, as shown in FIGS. 1-3, the adaptor apparatus **10** may include a latch mechanism for latching the socket lid assembly **120** to the socket base **102**. In one embodiment, the latch mechanism may include a latch element **108** connected to the lid portion **104** using a latch spring **109** (see FIG. 2) and a hinge pin and snap ring **107**. The latch element

108 engages the socket base **102** at indent **111** achieving a closed state (e.g., a latched state).

The exemplary adaptor shown in FIGS. 1-3 may further include various components. For example, the adaptor apparatus **10** may include a structure **112** for providing an arrangement of pins **136** (e.g., pogo pins) corresponding to the plurality of contact elements **16** of the packaged device **15** to which they are to be electrically connected. A pin and ball guide top layer **114** may be provided to guide the packaged device **15** and align the packaged device **15** to the arranged conductive elements **136** (e.g., pins, elements of an elastomer, etc.). Pin guide screws (not shown) may be provided for holding the arrangement of conductive elements **136** in position, and dowel pins **117** may be provided for the socket base **102** to align the conductive element containing structure **112** relative thereto. Further, an insulation plate **122**, a backing plate **118**, and socket base screws **121** are provided for mounting the adaptor body **101** relative to the target board **12** (e.g., a printed circuit board).

As previously described herein, the components forming the adaptor body **101** may take one of various different forms, and any particular listing and/or provision of description herein with respect to a particular adaptor body is not to be construed as limiting to the present disclosure. Further, for example, the arrangement of conductive elements to which the contact elements **16** of the packaged device are aligned and provided in electrical contact with by use of the socket lid assembly **120**, may take one of various different types or forms. For example, the arrangement of conductive elements may be provided by a conductive elastomer layer, a pin arrangement structure, a socket arrangement structure, or any other arrangement of conductive elements as would be known to one skilled in the art.

Further, in one or more embodiments, the socket lid assembly **120** may include one or more various additional components. For example, a compression plate **140** may be provided for transferring the force from the threaded interface member **22** to the packaged device **15**. However, such force may be applied directly from the threaded interface member **22** to the packaged device **15**. In one or more embodiments, the compression plate **140** may provide for a more distributed force on the packaged device **15**, and thus be advantageous.

The compression plate **140** of the socket lid assembly **120** may either be a floating compression plate upon which the threaded interface member **22** makes contact, or the compression plate **140** may be movably coupled to the socket lid assembly **120**, such as lid portion **104**, or any other component thereof. For example, as shown in FIGS. 1-3, the compression plate **140** includes threaded openings **148** for mating with clamshell screws **144** inserted within openings **150** of lid portion **104** to mount the compression plate **140** relative to the socket lid portion **104**. Clamshell screw springs **146** allow for the effective transmission of force from the threaded interface member **22** to the compression plate **140** when the compression plate **140** is mounted to the socket lid portion **104**.

As previously described herein, the components forming the socket lid assembly **120** may take one of various different forms, and any particular listing and/or provision of description herein with respect to a particular socket lid assembly is not to be construed as limiting to the present disclosure.

One or more embodiments of the adapter apparatus **10** shown in FIGS. 1-4 may be used to solve one or more issues relating to packaged device (e.g., semiconductor device) testing. For example, in a semiconductor test, accuracy is

critical. To test without permanently connecting the packaged device **15** (e.g., a chip) to a target board **12**, socket type adapter apparatus, such as adapter apparatus **10**, are used as interconnect material. Such socket type adapter apparatus may include an interface contact element structure (e.g., such as the arrangement of conductive elements **136** and the conductive element containing structure **112**) which interfaces the packaged device **15** to the target board **12**. Such an interface structure may degrade over usage. As such, socket type adapter apparatus may be rated for 2K to 500K cycles. However, measurement of the number of cycles which the interface contact element structure undergoes many difficult. Adapter apparatus **10** shown in FIGS. 1-4 includes an electronic insertion counter to provide such a measurement (e.g., count the number of times a packaged device **15** is compressed against the interface contact element structure providing for electrical connection of the packaged device as desired by the user).

To implement such an electronic insertion counter (e.g., a measurement apparatus), the adapter apparatus **10** includes an actuation apparatus **50** associated with the socket lid assembly **120**, counter circuitry **70**, and indicator **60**. The actuation apparatus **50** may be any apparatus that may be actuated when the socket lid assembly **120** closes the socket cavity **103** and applies a force upon the packaged device **15**. For example, the actuation apparatus **50** may include a compressible element located at a surface of the socket lid assembly **120** that is actuated upon contact with the packaged device **15** when the socket lid assembly **120** closes socket cavity **103** and applies a force upon the packaged device **15**. For example, the compressible element may be a spring-loaded element that produces a count or increment signal by closing a conductive path, may be a deflection element that produces a count or increment signal upon deflection, or may be any other actuator that upon contact with the packaged device **15** results in a measurement signal that increments a count of counter circuitry **70**.

For example, as shown in FIGS. 1-3, the socket lid assembly **120** includes a lower surface **123**. When the socket lid assembly **120** is closed (e.g., latched) the lower surface **123** faces towards the packaged device **15** and/or towards the socket cavity **103**. More specifically, the compression plate **140** includes the lower surface **123**. At least in one embodiment, as shown in FIGS. 1-3, the lower surface **123** is used to provide a force onto the packaged device **15** such that the plurality of contact elements **16** of the packaged device **15** are electrically connected to the conductive elements **136**. The actuation apparatus **50**, for example, as shown in FIGS. 1-3, includes a pushbutton **52** that extends through an opening **54** in compression plate **140** (e.g., the opening **54** terminating at the lower surface **123** thereof). The pushbutton **52** terminates at a surface **55** thereof exposed at the lower surface **123** such that when the socket lid assembly **120** closes the socket cavity **103** and the compression plate **140**, via surface **123**, applies a force upon packaged device **15**, the surface **55** of the pushbutton **52** contacts the packaged device **15** and is actuated (e.g., an increment count line to a microcontroller is closed as shown in FIG. 4). For example, the pushbutton **52** is deflected by the packaged device **15** into a void space **57** within compression plate **140**.

For example, as shown in FIG. 3A, the pushbutton **52** is in an uncompressed state, wherein a gap exists between surface **55** of the pushbutton **52** and the upper surface **190** of the packaged device **15**. Further, for example, as shown in FIG. 3B, the pushbutton **52** is in a compressed state (e.g.,

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such that a counter is incremented), wherein surface 55 of the pushbutton 52 is in contact with the upper surface 190 of the packaged device 15.

One skilled in the art will recognize that any actuation apparatus or configuration thereof, such as, for example, compressible actuators, spring-loaded actuators, rubber actuators, or the like, may be used to provide a measurement signal to counter circuitry 70. As such, the present disclosure is not limited to any particular type of actuator, but at least in one embodiment, actuation thereof provides a measurement signal indicating a count should be incremented.

Counter circuitry 70 may be any suitable circuitry for providing a counting function and generating an output for use by indicator 60. Such counter circuitry 70 may be implemented with the use of microprocessors, microcontrollers, analog circuitry, digital circuitry, and/or any hardware/software necessary to provide the functionality described herein. For example, as shown in FIG. 4, one embodiment of the counter circuitry 70 may include an increment line 71 with an actuation switch 72 operated in conjunction with an actuator, such as, for example, pushbutton 52. For example, the increment line 71 upon actuation of the actuator apparatus 50 (e.g., closing of switch 72) provides a count signal to microcontroller 73. Microcontroller 73 is programmed via the in circuit serial programmer 74 to count the actuations occurring in an incremental manner. In other words, each time an actuation occurs using, for example, the pushbutton 52, the microcontroller 73 increments the count. The microcontroller 73 may then provide a count parameter for display on indicator 60.

For example, in one or more embodiments, the count parameter may be a count of the number of times the actuation apparatus is actuated, the count parameter may be an indication that a certain count (e.g., count of cycles) has been reached, and/or any other count parameter based on the incremented count that may be beneficial to a user.

The indicator 60 may be any indicator suitable for providing a usable parameter to a user. For example, indicator 60 may be any suitable display, such as, for example, an LCD display, a mechanical rotary counter display for each digit, or the like.

The indicator 60, at least in one embodiment, is integrated into the socket lid assembly 120. For example, the indicator 60 may be a display viewable only when the socket lid assembly 120 is in an open state such that a packaged device may be received within the socket cavity 130. For example, as shown in FIG. 1, the display 60 is located (e.g., recessed in) at the lower surface 123 of the compression plate 140. However, the display 60 may be located at any other portion of the socket lid assembly 120, such as at a position that may be viewable when the socket lid assembly 120 is in a closed state (e.g., is latch and the socket lid assembly 120 covers the socket cavity 130). For example, display 60 may be located within the adapter apparatus 10, or on the top or side of the adapter apparatus 10 (e.g., socket lid assembly or adapter body).

Further, counter circuitry 70 may include a reset line 76 connected to the microcontroller 73 that includes a reset switch 77. At least in one embodiment, activation of the reset switch 77 resets the incremented count provided by the microcontroller 73 as driven by the actuation of increment line 71. For example, the reset switch 77 may reset the incremented count to zero. For example, if the interface contact element structure is replaced within the adapter apparatus 10, the user may reset the incremented count to zero. The reset switch 77 may be implemented in any suitable manner using an actuatable element. For example,

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as shown in FIG. 1, a reset switch 77 is provided within an opening 78 that terminates at the lower surface 123. For example, a pushbutton switch or any other suitable switch may be located within the opening and a user may activate the switch using an object insertable into the opening 78 at the lower surface 123.

At least in one embodiment, the counter circuitry 70 is integrated into the socket lid assembly 120. For example, the counter circuitry 70 may be located within the void 57 of the compression plate 140 (e.g., allowing easy connection to the display indicator 60 and the actuation apparatus 50, as well as the reset switch 77). However, the counter circuitry 70 may be located or positioned at any other portion of the socket lid assembly 120.

As such, and in operation, a method of testing packaged devices is provided using one or more embodiments of the adapter apparatus 10 described herein. For example, the method or operation may include positioning a packaged device 15 in the socket cavity 103, closing the socket lid assembly 120 to apply a force upon the packaged device 15 received in the socket cavity 130 of the adapter body 101 such that the plurality of contact elements of the packaged device 16 are electrically connected to conductive elements corresponding thereto. A counter is incremented upon closing of the socket lid assembly 120 and application of a force upon the packaged device 15 received in the socket cavity 103 of the adapter body 101. This process may be repeated for one or more additional packaged devices resulting in additional incremented counts. During the testing of one or more packaged devices, a count based on the incremented counter may be displayed, for example, using indicator 60 (e.g., "65" is displayed as an example on the indicator 60 of FIG. 1). A user may also reset the incremented counter, using, for example, reset switch 77.

In other words, at least in one or more embodiments, the electronic insertion counter may be integrated into the socket lid assembly 120. A pushbutton may be exposed on the compression plate 140 which compresses the packaged device 15 onto the target board 12 via interface conductive elements. At least in one or more embodiments, every time a packaged device is compressed, the pushbutton is actuated which in turn activates the counter circuitry 70 integrated into the socket lid assembly 120. Such actuations (e.g., activations) are counted by the counter circuitry 70 and may be displayed by the indicator 60 (e.g., an LCD display). For example, if an interface conductive element structure is rated for 2K insertions, then after 2K insertions are measured in accordance with the features described herein, the interface conductive element structure may be replaced. The counter circuitry can then be reset to count from zero (e.g., "0" may be displayed on the indicator 60).

A perspective view of another embodiment of an exemplary packaged device adaptor apparatus 200 that includes temperature monitoring is shown in FIG. 5. The exemplary packaged device adaptor apparatus 200 may be mounted relative to a target board 12 (e.g., such as shown in FIG. 7). A top view of the exemplary packaged device adaptor apparatus 200 is shown in FIG. 2. FIGS. 7A and 7B are cross-section views of the exemplary adapter apparatus 200 shown in FIGS. 5-6 taken along line A-A in FIG. 6, in an open and closed position or state, respectively.

The adaptor apparatus 200 is for use with a packaged device 15 (see FIGS. 7A and 7B) having a plurality of contact elements 16 disposed on a surface 192 (e.g., bottom surface) thereof. The adaptor apparatus 200 includes an adaptor body 301 and a socket lid assembly 320. The adaptor body 301 defines a least part of a socket cavity 303 (see FIG.

7) configured to receive the packaged device **15** such that, for example, the plurality of contact elements **16** of the packaged device **15** may be aligned with arranged conductive elements. For example, the conductive elements may include conductive elements **336** as shown in FIGS. 7A and 7B which may form a portion of adaptor apparatus **200**. However, the conductive elements may include other elements in one or more other applications as will be apparent from the description herein, such as, for example, an arranged pattern of contacts on a surface (e.g., a surface **18** of a target board **12**). As shown in FIG. 5, the adapter apparatus **200** is in a closed state (e.g., the lid assembly **320** is in a closed position such that the socket lid assembly **320** closes the socket cavity **303** and applies a force to a packaged device **15** received within the socket cavity **303**).

The socket lid assembly **320** includes a lid portion **304** and a torque assembly **220** provided to assist in applying a force upon the packaged device **15** received in the socket cavity **303** defined by the adaptor body **301**. In at least one embodiment, the torque assembly **220** includes a threaded interface member **222**; the threaded interface member **222** including a threaded portion **230** configured to mate with the threaded opening **305** of the lid portion **304**. Further, at least in one embodiment, the torque assembly **220** includes a torque applicator **224** for grasping and applying torque (e.g., the torque applicator **224** being coupled to the threaded interface member **222** such that torque applied to the torque applicator **224** is transferred to the threaded interface member **222** to move the threaded portion **230** thereof into the threaded opening **305** of the lid portion **304**. Turning of the torque assembly **220** into the threaded opening **305** may assist in asserting a force (e.g., either directly or indirectly) onto packaged device **15** such as, for example, to provide the contact elements **16** of the packaged device **15** into electrical contact with an arrangement of conductive elements (e.g., conductive elements **336**, elements of a conductive elastomer, etc.) corresponding thereto.

In one embodiment, the components of the adaptor apparatus **200** (e.g., including the socket lid assembly **320** which may include torque assembly **220** and lid portion **304**, the adaptor body **301**, and the socket cavity **303**) may lie along axis **311**. The axis **311** is generally orthogonal, at least in one embodiment, to the target board **12**.

The packaged device **15** may be any packaged device such as described with reference to FIGS. 1-3, for example, as shown in FIGS. 7A and 7B, packaged device **15** includes an upper surface **190** and the lower surface **192**, in addition to one or more side surfaces extending therebetween at the perimeter of the packaged device **15**. The plurality of contact elements **16**, for example, may be disposed at least at the lower surface **192**.

Substantially as described with reference adapter body **101** and socket lid assembly **120**, the adaptor body **301** may be provided by any number of components that define the socket cavity **303** configured to receive the packaged device **15** therein and the socket lid assembly **320** may be provided by any number of components that are configured to close the socket cavity **303** and apply a force to a packaged device received therein.

As shown in FIGS. 5-7, the adaptor body **301** (e.g., a part of a clamshell socket) includes a socket base **302** defining at least a part of the socket cavity **303** therein configured to receive a packaged device **15**. The socket lid assembly **320** used to close the socket cavity **303** may be hinged to the socket base **302** using a hinge pin or pins **306**. However, as shown in FIGS. 5-7, the adaptor apparatus **200** may include a latch mechanism on opposing sides of the adaptor appa-

ratus **200** for latching the socket lid assembly **320** to the socket base **302**. In one embodiment, the latch mechanism may include a latch element **308** connected to the lid portion **304** using a latch spring **309** (see FIG. 6) and a hinge pin and snap ring **307**. The latch element **308** engages the socket base **302** at indent **311** achieving a closed and latched state.

The exemplary adaptor apparatus **200** shown in FIGS. 5-7 may further include various components. For example, the adaptor apparatus **200** may include a structure **312** for providing an arrangement of pins **336** (e.g., pogo pins) corresponding to the plurality of contact elements **16** of the packaged device **15** to which they are to be electrically connected. A pin and ball guide top layer **314** may be provided to guide the packaged device **15** and align the packaged device **15** to the arranged conductive elements **336** (e.g., pins, elements of an elastomer, etc.). Pin guide screws (not shown) may be provided for holding the arrangement of conductive elements **336** in position, and dowel pins **317** may be provided for the socket base **302** to align the conductive element containing structure **312** relative thereto. Further, an insulation plate **322**, a backing plate **318**, and socket base screws **321** may be provided for mounting the adaptor body **301** relative to the target board **12** (e.g., a printed circuit board).

As previously described herein, the components forming the adaptor body **301** may take one of various different forms, and any particular listing and/or provision of description herein with respect to a particular adaptor body is not to be construed as limiting to the present disclosure. Further, for example, the arrangement of conductive elements to which the contact elements **16** of the packaged device are aligned and provided in electrical contact with by use of the socket lid assembly **320**, may take one of various different types or forms. For example, the arrangement of conductive elements may be provided by a conductive elastomer layer, a pin arrangement structure, a socket arrangement structure, or any other arrangement of conductive elements as would be known to one skilled in the art.

Further, in one or more embodiments, the socket lid assembly **320** may include one or more various additional components. For example, a compression plate **340** may be provided for transferring the force from the threaded interface member **222** to the packaged device **15**. However, such force may be applied directly from the threaded interface member **222** to the packaged device **15**. In one or more embodiments, the compression plate **340** may provide for a more distributed force on the packaged device **15**, and thus be advantageous.

The compression plate **340** of the socket lid assembly **320** may either be a floating compression plate upon which the threaded interface member **222** makes contact, or the compression plate **340** may be movably coupled to the socket lid assembly **320**, such as lid portion **304**, or any other component thereof. For example, as shown in FIGS. 5-7, the compression plate **340** includes threaded openings **348** for mating with clamshell screws **344** inserted within openings **350** of lid portion **304** to mount the compression plate **340** relative to the socket lid portion **304**. Clamshell screw springs **346** allow for the effective transmission of force from the threaded interface member **222** to the compression plate **340** when the compression plate **340** is mounted to the socket lid portion **304**.

As previously described herein, the components forming the socket lid assembly **320** may take one of various different forms, and any particular listing and/or provision of

description herein with respect to a particular socket lid assembly is not to be construed as limiting to the present disclosure.

Further, one or more embodiments of the adapter apparatus **200** shown in FIGS. **5-8** may be used to solve one or more issues relating to the functionality of the packaged device (e.g., semiconductor device) under test (e.g., a temperature or other measurable parameter or characteristic of the packaged device a user may desire may be measured, such as force, etc.). For example, in a semiconductor test, packaged device **15** (e.g., a chip) functioning may be affected by the temperature of the packaged device **15**. For example, when the packaged devices operate at a certain power, heat is generated. If heat is not properly dissipated, the packaged device functionality may be in error. Such that heat may be properly dissipated, it is important to have an accurate measurement of the temperature of the packaged device **15**. The apparatus **200** shown in FIGS. **5-8** includes electronic temperature monitoring to provide such a temperature measurement (e.g., the temperature of a packaged device **15** is measured using a sensing element in contact with the packaged device **15**).

To implement such electronic temperature measurement, the adapter apparatus **200** includes a temperature sensing apparatus **250** associated with the socket lid assembly **320**, temperature measurement circuitry **270**, and indicator **260**. The temperature sensing apparatus **250** may be any measurement element suitable for sensing temperature of the packaged device **15** when the socket lid assembly **320** closes the socket cavity **303** and applies a force upon the packaged device **15**. For example, the measurement element may include a temperature sensor located at a surface of the socket lid assembly **320** that comes into contact with the packaged device **15** when the socket lid assembly **320** closes socket cavity **303** and applies a force upon the packaged device **15**. For example, the temperature sensor may be a thermocouple for use in generating a measurement signal representative of the temperature of the packaged device **15**, may be a temperature sending pad that changes color due to heat, or may be any other transducer suitable to generate a measurement signal representative of the temperature of the packaged device **15** for use, for example, by signal processing circuitry to drive an indicator (e.g., display, color, etc.).

For example, as shown in FIGS. **5-7**, the socket lid assembly **320** includes a lower surface **323**. When the socket lid assembly **320** is closed (e.g., latched) the lower surface **323** faces towards the packaged device **15** and/or towards the socket cavity **303**. More specifically, the compression plate **340** includes the lower surface **323**. At least in one embodiment, as shown in FIGS. **5-7**, the lower surface **323** is used to provide a force onto the packaged device **15** such that the plurality of contact elements **16** of the packaged device **15** are electrically connected to the conductive elements **336**. The temperature sensing apparatus **250**, for example, as shown in FIGS. **5-7**, includes a thermocouple **252** that extends through an opening **254** in compression plate **340** (e.g., the opening **254** terminating at the lower surface **323** thereof). The thermocouple **252** terminates at a sensing end surface **255** exposed at the lower surface **323** such that when the socket lid assembly **320** closes the socket cavity **303** and the compression plate **340**, via surface **323**, applies a force upon packaged device **15** the surface **255** of the thermocouple **252** contacts the packaged device **15** and senses temperature of the packaged device **15** (e.g., a transducer measurement signal is provided to signal processing circuitry as shown in FIG. **8**).

For example, as shown in FIG. **7A**, the thermocouple **252** is in an open position, wherein a gap exists between sensing end surface **255** of the thermocouple **252** and the upper surface **190** of the packaged device **15**. Further, for example, as shown in FIG. **7B**, the thermocouple **252** is in a closed state (e.g., such that a temperature measurement signal is provided for use in driving a temperature display), wherein surface **255** of the thermocouple **252** is in contact with the upper surface **190** of the packaged device **15**. The thermocouple **252** may be configured to be deflectable or spring loaded (e.g., movable within the opening **254** as pressure is applied to the device under test **15** when surface **255** contact the device **15**). As such, a proper contact pressure may be achieved for providing an accurate temperature measurement signal.

Temperature measurement circuitry **270** may be any suitable circuitry for providing a temperature sensing function and generating an output for use by indicator **260**. Such temperature measurement circuitry **270** may be implemented with the use of microprocessors, microcontrollers, analog circuitry, digital circuitry, and/or any hardware/software necessary to provide the functionality described herein. For example, as shown in FIG. **8**, one embodiment of the temperature measurement circuitry **270** may include a measurement signal line **271** for providing a temperature measurement signal to signal processing circuitry **272** from temperature sensing apparatus **250** (e.g., a transducer, such as thermocouple **252**). Signal processing circuitry **272** may include an amplifier and analog-to-digital converter circuitry for use in processing the measurement signal from temperature sensing apparatus **250**. Further, the signal processing circuitry **272** may include display decoder functionality to drive indicator **260**. In other words, for example, the thermocouple **252** provides the temperature measurement signal and the signal processing circuitry **272** processes the signal and provides a temperature parameter for display on indicator **260**.

For example, in one or more embodiments, the temperature parameter may be a numerical temperature for display, the temperature parameter may be an indication that a certain temperature (e.g., indicating excessive heat) has been reached, and/or any other temperature parameter based on the temperature measurement signal that may be beneficial to a user. The indicator **260** may be any indicator suitable for providing a usable parameter to a user. For example, indicator **260** may be any suitable display, such as, for example, an LCD display, or the like.

The indicator **260**, at least in one embodiment, may be integrated into the socket lid assembly **320**. For example, the indicator **260** may be a display viewable only when the socket lid assembly **320** is in a closed state (e.g., is latched and the socket lid assembly **320** covers the socket cavity **303**). For example, display **260** may be located on the outside of the adapter apparatus **200**, such as on the top or side of the adapter apparatus **200** (e.g., the socket lid assembly).

At least in one embodiment, the temperature measurement circuitry **270** is integrated into the socket lid assembly **320**. For example, the temperature measurement circuitry **270** may be located within a void **257** of the torque assembly **220** (e.g., allowing easy connection to the display indicator **260** and the temperature sensing apparatus **250**). However, the temperature measurement circuitry **270** may be located at any other portion of the socket lid assembly **320** (e.g., compression plate, etc.).

As such, and in operation, a method of testing packaged devices is provided using one or more embodiments of the

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adapter apparatus **200** described herein. For example, the method or operation may include positioning a packaged device **15** in the socket cavity **230**, closing the socket lid assembly **320** to apply a force upon the packaged device **15** received in the socket cavity **303** of the adapter body **301** such that the plurality of contact elements of the packaged device **15** are electrically connected to conductive elements corresponding thereto. A temperature sensing apparatus is configured to touch a packaged device **15** received in the socket cavity **303** to sense the temperature of the packaged device **15** when the socket lid assembly **320** closes the socket cavity **303** and applies a force upon the packaged device **15**. During the testing of one or more packaged devices, a temperature parameter based on the temperature measurement signal may be displayed, for example, using indicator **260**.

In other words, at least in one or more embodiments, the electronic temperature monitoring may be integrated into the socket lid assembly **320** (e.g., the lid portion **304**, the compression knob, etc.). A thermocouple sensor **252** may be electrically connected and may be exposed on the compression plate **340** which compresses the packaged device **15** onto the target board **12**. At least in one or more embodiments, when a packaged device **15** is compressed, the thermocouple **252** touches the upper surface **190** of the packaged device **15** to enable sampling of the temperature measurement signal by the signal processing circuitry **272**. The thermocouple **252** may be spring-loaded to achieve a proper pressure on the upper surface **190** of the packaged device **15**. Power may be applied to the packaged device to start its operation or function. As the packaged device starts to function, heat is generated. The heat is sensed by the thermocouple **252** and a measurement signal representative thereof is fed to the signal processing circuitry **272** where it is processed and may be displayed by the indicator **260** (e.g., an LCD display).

All patents and references cited herein are incorporated in their entirety as if each were incorporated separately. This disclosure has been provided with reference to illustrative embodiments and is not meant to be construed in a limiting sense. As described previously, one skilled in the art will recognize that various other illustrative adapter assembly embodiments may be provided which utilize various combinations of the elements described herein. Various modifications of the illustrative embodiments, as well as additional embodiments of the disclosure and combinations of various elements herein, will be apparent to persons skilled in the art upon reference to this description. It is therefore contemplated that the patented claims will cover any such modifications or embodiments that may fall within the scope of the present invention as defined by the accompanying claims.

What is claimed is:

1. An adapter apparatus for use with a packaged device having a plurality of contact elements disposed on a surface thereof, the adapter apparatus comprising:

an adapter body defining a socket cavity configured to receive a packaged device;

a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto;

an actuation apparatus associated with the socket lid assembly, wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, and further wherein the actuation apparatus associated with

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the socket lid assembly comprises a compressible element at a surface of the socket lid assembly that is actuated upon contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device;

counter circuitry configured to increment a count when the actuation apparatus is actuated; and

an indicator configured to display a parameter based on the incremented count.

2. The adapter apparatus of claim **1**, wherein the indicator is configured to display a count of the number of times the actuation apparatus is actuated.

3. The adapter apparatus of claim **2**, wherein the adapter apparatus comprises reset circuitry to reset the count to zero.

4. The adapter apparatus of claim **1**, wherein the indicator comprises a display viewable only when the socket lid assembly is in an open state such that a packaged device may be received within the socket cavity.

5. The adapter apparatus of claim **1**, wherein the counter circuitry is integrated into the socket lid assembly.

6. The adapter apparatus of claim **1**, wherein the adapter apparatus further comprises:

a temperature sensing apparatus associated with the socket lid assembly, wherein the temperature sensing apparatus comprises a sensing element that is configured to touch a packaged device received in the socket cavity to sense the temperature of the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device; and

a temperature indicator configured to display a parameter based on the sensed temperature.

7. A method of testing packaged devices using an adapter apparatus, wherein each of the packaged devices comprise a plurality of contact elements disposed on a surface thereof, wherein the method comprises:

providing an adapter body defining a socket cavity therein configured to receive a packaged device;

providing a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto;

positioning a packaged device in the socket cavity;

closing the socket lid assembly to apply a force upon the packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto; and

incrementing a counter upon closing the socket lid assembly and applying a force upon the packaged device received in the socket cavity of the adapter body, wherein incrementing the counter upon closing the socket lid assembly comprises:

providing an actuation apparatus associated with the socket lid assembly, wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, and further wherein the actuation apparatus associated with the socket lid assembly comprises a compressible element at a surface of the socket lid assembly that is actuated upon contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, and

incrementing a counter based on the actuation of the actuation apparatus.

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8. The method of claim 7, wherein the method further comprises:

repeating the positioning of a packaged device in the socket cavity, closing the socket lid assembly to apply a force upon the packaged device received in the socket cavity of the adapter body, and incrementing a counter upon closing the socket lid assembly for one or more additional packaged devices; and displaying a count based on the incremented counter.

9. The method of claim 8, wherein the method further comprises resetting the incremented counter.

10. The method of claim 8, wherein displaying the count comprises displaying the count only when the socket lid assembly is in an open state such that a packaged device may be received within the socket cavity.

11. The method of claim 7, wherein the method further comprises displaying a temperature of the packaged device upon closing the socket lid assembly and applying a force upon the packaged device received in the socket cavity of the adapter body.

12. An adapter apparatus for use with a packaged device having a plurality of contact elements disposed on a surface thereof, the adapter apparatus comprising:

an adapter body defining a socket cavity configured to receive a packaged device;

a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto;

a measurement apparatus associated with the socket lid assembly, wherein the measurement apparatus comprises a measurement element that is configured to contact a packaged device received in the socket cavity when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, wherein a measurement signal is generated with use of the measurement element that is configured to contact the packaged device, wherein the measurement apparatus comprises an actuation apparatus associated with the socket lid assembly, wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon a packaged device, wherein the actuation apparatus associated with the socket lid assembly comprises a compressible element as the measurement element at a surface of the socket lid assembly that is actuated upon contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device; and

an indicator configured to display a parameter based on the measurement signal, wherein the indicator is configured to display a count of the number of times the actuation apparatus is actuated.

13. The adapter apparatus of claim 12, wherein the measurement apparatus associated with the socket lid assembly comprises a temperature sensing apparatus associated with the socket lid assembly, wherein the temperature sensing apparatus comprises a sensing element that is configured to touch a packaged device received in the socket cavity to sense the temperature of the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, and further wherein the indicator is configured to display a parameter based on the sensed temperature.

14. The adapter apparatus of claim 13, wherein the measurement element comprises a thermocouple configured

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at a surface of the socket lid assembly such that the thermocouple is in contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device.

15. The adapter apparatus of claim 13, wherein the indicator is viewable when the socket lid assembly is in a closed state when the socket lid assembly closes the socket cavity and applies a force upon a packaged device received within the socket cavity.

16. The adapter apparatus of claim 12, wherein the measurement apparatus further comprises measurement and display circuitry integrated into the socket lid assembly.

17. A method of testing packaged devices using an adapter apparatus, wherein each of the packaged devices comprise a plurality of contact elements disposed on a surface thereof, wherein the method comprises:

providing an adapter body defining a socket cavity therein configured to receive a packaged device;

providing a socket lid assembly configured to apply a force upon a packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto;

providing a measurement apparatus associated with the socket lid assembly, wherein the measurement apparatus comprises a measurement element that is configured to contact a packaged device received in the socket cavity when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, and further wherein providing the measurement apparatus comprises providing an actuation apparatus associated with the socket lid assembly, wherein the actuation apparatus associated with the socket lid assembly comprises a compressible element as the measurement element at a surface of the socket lid assembly that is actuated upon contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device, wherein the actuation apparatus is actuated when the socket lid assembly closes the socket cavity and applies a force upon a packaged device;

positioning a packaged device in the socket cavity; closing the socket lid assembly to apply a force upon the packaged device received in the socket cavity of the adapter body such that the plurality of contact elements of the packaged device are electrically connected to conductive elements corresponding thereto and generating a measurement signal using the measurement element;

incrementing a counter upon closing the socket lid assembly, wherein incrementing the counter upon closing the socket lid assembly comprises incrementing the counter based on the actuation of the actuation apparatus; and

displaying a parameter based on the measurement signal, wherein displaying the parameter based on the measurement signal comprises displaying a count of the number of times the actuation apparatus is actuated.

18. The method of claim 17, wherein providing the measurement apparatus comprises providing a temperature sensing apparatus associated with the socket lid assembly, wherein the temperature sensing apparatus comprises a temperature sensing element that is configured to touch a packaged device received in the socket cavity to sense the temperature of the packaged device when the socket lid assembly closes the socket cavity and applies a force upon

the packaged device, and further wherein displaying a parameter based on the measurement signal comprises displaying a parameter based on the sensed temperature.

19. The method of claim 18, wherein the sensing element comprises a thermocouple configured at a surface of the socket lid assembly such that the thermocouple is in contact with the packaged device when the socket lid assembly closes the socket cavity and applies a force upon the packaged device. 5

20. The method of claim 18, wherein displaying a parameter based on the sensed temperature comprises displaying a temperature at a location viewable when the socket lid assembly is in a closed state when the socket lid assembly closes the socket cavity and applies a force upon a packaged device received within the socket cavity. 15

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